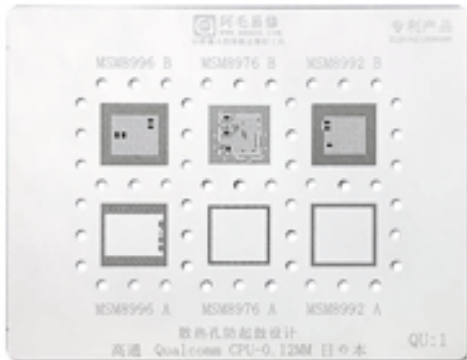


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## BGA stencils for Qualcomm CPU (QU: 1) 0.12mm

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Product ID: 22176

Price: **12.00 EUR**

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Product weight: **0.01 kg**

### Description:

BGA stencils for Qualcomm CPU (QU: 1) 0.12mm allows reballing 3 models: MSM8996B, MSM8976B, MSM8992B, MSM8996A, MSM8976A, MSM8992A.

#### Contact details:

Telefon: +48 17 227 00 25  
Infolinia: 0 801 671 717  
E-mail: [biuro@multi-com.pl](mailto:biuro@multi-com.pl)  
Skype: Multi-COM

#### Address:

Multi-COM Sp. z o.o.  
ul. Stanisława Krzaklewskiego 31b  
36-100 Kolbuszowa  
POLSKA

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